

Abstract

The present invention relates to a novel photoresist composition sensitive to
5 radiation in the deep ultraviolet and a process for imaging the composition. The
photoresist composition comprises a) a novel polymer that is insoluble in an
aqueous alkaline solution and comprises at least one acid labile group, and b) a
compound capable of producing an acid upon irradiation. The novel polymer of
the present invention comprises at least one unit with a bisester group,
10 (-C(O)OWC(O)O-), attached on one side to a polymer backbone unit (A)
comprising an aliphatic group, and attached on the other side to an adamantyl
group. The invention also relates to the novel polymer and a novel monomer for
obtaining the novel polymer.